862.C2261



PATENT APPLICATION

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of: TAKASHI ARAI		Examiner: Not Yet Assigned Group Art Unit: 1732
Filed: J	une 11, 2001	
For:	FOAM MOLDING METHOD AND)	Sentember 13, 2001

Commissioner for Patents Washington, D.C. 20231

PRELIMINARY AMENDMENT

Sir:

PECENED TO I POO Prior to examining the subject application on the merits, please amend this application as follows and consider the following remarks.

IN THE SPECIFICATION:

Please replace a paragraph beginning at page 9, line 13 and ending at page 9, line 19 with the following paragraph. A marked-up copy of this paragraph showing the changes thereto is attached.

-- If a molded product made of a resin material is to be used as a mount member, consideration should be given to a reduction in weight. As a technique of reducing the weight of a resin molded member, a molding method of foaming a resin material is disclosed in USP 4360484, USP 4473665 and Japanese Patent Laid-Open No. 8-300392.--